ESP32-S2-WROOM & ESP32-S2-WROOM-I

User Manual

Prerelease version 0.5

Espressif Systems

About This Document

This document provides the specifications for the ESP32-S2-WROOM and ESP32-S2-WROOM-I module.

Document Updates

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1. Module Overview

1.1 Features

MCU

- ESP32-S2 embedded, Xtensa® single-core 32-bit LX7 microprocessor, up to 240 MHz
- 128 KB ROM
- 320 KB SRAM
- 16 KB SRAM in RTC

Wi-Fi

- 802.11 b/g/n
- Bit rate: 802.11n up to 150 Mbps
- A-MPDU and A-MSDU aggregation
- 0.4 μs guard interval support
- Center frequency range of operating channel: 2412 ~ 2462 MHz

Hardware

- Interfaces: GPIO, SPI, LCD, UART, I^2C, I^2S, Camera interface, IR, pulse counter, LED PWM, USB OTG 1.1, ADC, DAC, touch sensor, temperature sensor
- 40 MHz crystal oscillator
- 4 MB SPI flash
- Operating voltage/Power supply: 3.0 ~ 3.6 V
- Operating temperature range: –40 ~ 85 °C
- Dimensions: (18 × 31 × 3.3) mm

Certification

- Green certification: RoHS/REACH
- RF certification: FCC/CE-RED/SRRC

Test

- HTOL/HTSL/uHAST/TCT/ESD

1.2 Description

ESP32-S2-WROOM and ESP32-S2-WROOM-I are two powerful, generic Wi-Fi MCU modules that have a rich set of peripherals. They are an ideal choice for a wide variety of application scenarios relating to Internet of Things (IoT), wearable electronics and smart home.

ESP32-S2-WROOM comes with a PCB antenna, and ESP32-S2-WROOM-I with an IPEX antenna. They both feature a 4 MB external SPI flash. **The information in this datasheet is applicable to both modules.**

The ordering information of the two modules is listed as follows:

Table 1: Ordering Information

Module	Chip embedded	Flash	Module dimensions (mm)
ESP32-S2-WROOM (PCB)	ESP32-S2	4 MB	(18.00±0.15)×(31.00±0.15)×(3.30±0.15)
ESP32-S2-WROOM-I (IPEX)			
Notes: 1. The module with various capacities of flash is available for custom order. 2. For dimensions of the IPEX connector, please see Section 7.3.			

At the core of this module is ESP32-S2 *, an Xtensa® 32-bit LX7 CPU that operates at up to 240 MHz. The chip has a low-power co-processor that can be used instead of the CPU to save power while performing tasks that do not require much computing power, such as monitoring of peripherals. ESP32-S2 integrates a rich set of peripherals, ranging from SPI, I²S, UART, I²C, LED PWM, LCD, Camera interface, ADC, DAC, touch sensor, temperature sensor, as well as up to 43 GPIOs. It also includes a full-speed USB On-The-Go (OTG) interface to enable USB communication.

Note:

* For more information on ESP32-S2, please refer to *ESP32-S2 Datasheet*.

1.3 Applications

- Generic Low-power IoT Sensor Hub
- Generic Low-power IoT Data Loggers
- Cameras for Video Streaming
- Over-the-top (OTT) Devices
- USB Devices
- Speech Recognition
- Image Recognition
- Mesh Network
- Home Automation
- Smart Home Control Panel
- Smart Building
- Industrial Automation
- Smart Agriculture
- Audio Applications
- Health Care Applications
- Wi-Fi-enabled Toys
- Wearable Electronics
- Retail & Catering Applications
- Smart POS Machines

2. Pin Definitions

2.1 Pin Layout

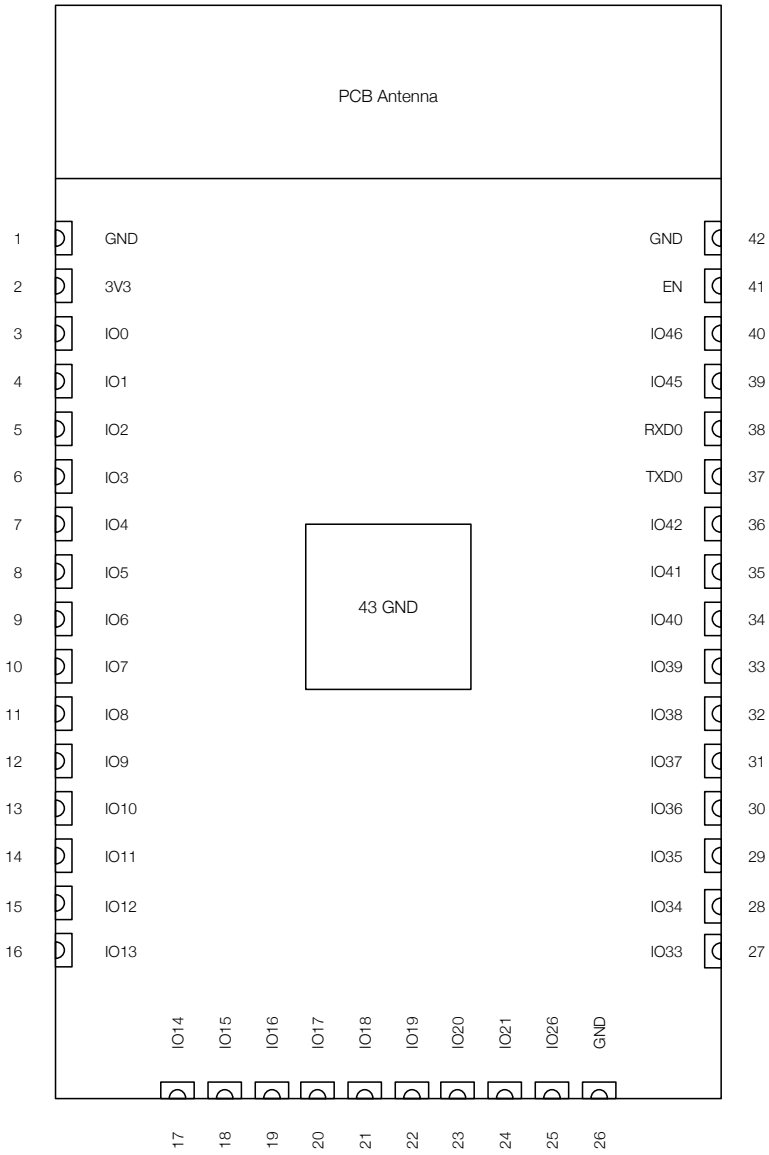


Figure 1: Module Pin Layout (Top View)

Note:
The pin diagram shows the approximate location of pins on the module. For the actual mechanical diagram, please refer to Figure 7.1 *Physical Dimensions*.

2.2 Pin Description

The module has 42 pins. See pin definitions in Table 2.

Table 2: Pin Definitions

Name	No.	Type	Function
GND	1	P	Ground
3V3	2	P	Power supply
IO0	3	I/O/T	RTC_GPIO0, GPIO0
IO1	4	I/O/T	RTC_GPIO1, GPIO1, TOUCH1, ADC1_CH0
IO2	5	I/O/T	RTC_GPIO2, GPIO2, TOUCH2, ADC1_CH1
IO3	6	I/O/T	RTC_GPIO3, GPIO3, TOUCH3, ADC1_CH2
IO4	7	I/O/T	RTC_GPIO4, GPIO4, TOUCH4, ADC1_CH3
IO5	8	I/O/T	RTC_GPIO5, GPIO5, TOUCH5, ADC1_CH4
IO6	9	I/O/T	RTC_GPIO6, GPIO6, TOUCH6, ADC1_CH5
IO7	10	I/O/T	RTC_GPIO7, GPIO7, TOUCH7, ADC1_CH6
IO8	11	I/O/T	RTC_GPIO8, GPIO8, TOUCH8, ADC1_CH7
IO9	12	I/O/T	RTC_GPIO9, GPIO9, TOUCH9, ADC1_CH8, FSPIHD
IO10	13	I/O/T	RTC_GPIO10, GPIO10, TOUCH10, ADC1_CH9, FSPICS0, FSPIIO4
IO11	14	I/O/T	RTC_GPIO11, GPIO11, TOUCH11, ADC2_CH0, FSPID, FSPIIO5
IO12	15	I/O/T	RTC_GPIO12, GPIO12, TOUCH12, ADC2_CH1, FSPICLK, FSPIIO6
IO13	16	I/O/T	RTC_GPIO13, GPIO13, TOUCH13, ADC2_CH2, FSPIQ, FSPIIO7
IO14	17	I/O/T	RTC_GPIO14, GPIO14, TOUCH14, ADC2_CH3, FSPIWP, FSPIDQS
IO15	18	I/O/T	RTC_GPIO15, GPIO15, U0RTS, ADC2_CH4, XTAL_32K_P
IO16	19	I/O/T	RTC_GPIO16, GPIO16, U0CTS, ADC2_CH5, XTAL_32K_N
IO17	20	I/O/T	RTC_GPIO17, GPIO17, U1TXD, ADC2_CH6, DAC_1
IO18	21	I/O/T	RTC_GPIO18, GPIO18, U1RXD, ADC2_CH7, DAC_2, CLK_OUT3
IO19	22	I/O/T	RTC_GPIO19, GPIO19, U1RTS, ADC2_CH8, CLK_OUT2, USB_D-
IO20	23	I/O/T	RTC_GPIO20, GPIO20, U1CTS, ADC2_CH9, CLK_OUT1, USB_D+
IO21	24	I/O/T	RTC_GPIO21, GPIO21
IO26	25	I/O/T	SPICS1, GPIO26
GND	26	P	Ground
IO33	27	I/O/T	SPIIO4, GPIO33, FSPIHD
IO34	28	I/O/T	SPIIO5, GPIO34, FSPICS0
IO35	29	I/O/T	SPIIO6, GPIO35, FSPID
IO36	30	I/O/T	SPIIO7, GPIO36, FSPICLK
IO37	31	I/O/T	SPIDQS, GPIO37, FSPIQ
IO38	32	I/O/T	GPIO38, FSPIWP
IO39	33	I/O/T	MTCK, GPIO39, CLK_OUT3
IO40	34	I/O/T	MTDO, GPIO40, CLK_OUT2
IO41	35	I/O/T	MTDI, GPIO41, CLK_OUT1
IO42	36	I/O/T	MTMS, GPIO42
TXD0	37	I/O/T	U0TXD, GPIO43, CLK_OUT1
RXD0	38	I/O/T	U0RXD, GPIO44, CLK_OUT2
IO45	39	I/O/T	GPIO45
IO46	40	I	GPIO46

Name	No.	Type	Function
EN	41	I	High: on, enables the chip. Low: off, the chip powers off. Note: Do not leave the EN pin floating.
GND	42	P	Ground

Notice:

For peripheral pin configurations, please refer to *ESP32-S2 User Manual*.

2.3 Strapping Pins

ESP32-S2 has three strapping pins: GPIO0, GPIO45, GPIO46. The pin-pin mapping between ESP32-S2 and the module is as follows, which can be seen in Chapter 5 *Schematics*:

- GPIO0 = IO0
- GPIO45 = IO45
- GPIO46 = IO46

Software can read the values of corresponding bits from register "GPIO_STRAPPING".

During the chip's system reset (power-on-reset, RTC watchdog reset, brownout reset, analog super watchdog reset, and crystal clock glitch detection reset), the latches of the strapping pins sample the voltage level as strapping bits of "0" or "1", and hold these bits until the chip is powered down or shut down.

IO0, IO45 and IO46 are connected to the internal pull-up/pull-down. If they are unconnected or the connected external circuit is high-impedance, the internal weak pull-up/pull-down will determine the default input level of these strapping pins.

To change the strapping bit values, users can apply the external pull-down/pull-up resistances, or use the host MCU's GPIOs to control the voltage level of these pins when powering on ESP32-S2.

After reset, the strapping pins work as normal-function pins.

Refer to Table 3 for a detailed boot-mode configuration of the strapping pins.

Table 3: Strapping Pins

VDD_SPI Voltage [1]			
Pin	Default	3.3 V	1.8 V
IO45 [2]	Pull-down	0	1
Booting Mode			
Pin	Default	SPI Boot	Download Boot
IO0	Pull-up	1	0
IO46	Pull-down	Don't-care	0
Enabling/Disabling ROM Code Print During Booting [3] [4]			
Pin	Default	Enabled	Disabled
IO46	Pull-down	See the fourth note	See the fourth note

Note:

1. Firmware can configure register bits to change the settings of "VDD_SPI Voltage".
2. Internal pull-up resistor (R1) for IO45 is not populated in the module, as the flash in the module works at 3.3 V by default (output by VDD_SPI). Please make sure IO45 will not be pulled high when the module is powered up by external circuit.
3. ROM code can be printed over TXD0 (by default) or DAC_1 (IO17), depending on the eFuse bit.
4. When eFuse UART_PRINT_CONTROL value is:
   0, print is normal during boot and not controlled by IO46.
   1 and IO46 is 0, print is normal during boot; but if IO46 is 1, print is disabled.
   2 and IO46 is 0, print is disabled; but if IO46 is 1, print is normal.
   3, print is disabled and not controlled by IO46.

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 4: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
VDD33	Power supply voltage	–0.3	3.6	V
T_{STORE}	Storage temperature	–40	85	°C

3.2 Recommended Operating Conditions

Table 5: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDD33	Power supply voltage	3.0	3.3	3.6	V
I_{VDD}	Current delivered by external power supply	0.5	—	—	A
T	Operating temperature	–40	—	85	°C
Humidity	Humidity condition	—	85	—	%RH

3.3 DC Characteristics (3.3 V, 25 °C)

Table 6: DC Characteristics (3.3 V, 25 °C)

Symbol	Parameter	Min	Typ	Max	Unit
C_{IN}	Pin capacitance	—	2	—	pF
V_{IH}	High-level input voltage	0.75 × VDD	—	VDD + 0.3	V
V_{IL}	Low-level input voltage	–0.3	—	0.25 × VDD	V
I_{IH}	High-level input current	—	—	50	nA
I_{IL}	Low-level input current	—	—	50	nA
V_{OH}	High-level output voltage	0.8 × VDD	—	—	V
V_{OL}	Low-level output voltage	—	—	0.1 × VDD	V
I_{OH}	High-level source current (VDD = 3.3 V, V_{OH} >= 2.64 V, PAD_DRIVER = 3)	—	40	—	mA
I_{OL}	Low-level sink current (VDD = 3.3 V, V_{OL} = 0.495 V, PAD_DRIVER = 3)	—	28	—	mA
R_{PU}	Pull-up resistor	—	45	—	kΩ
R_{PD}	Pull-down resistor	—	45	—	kΩ
V_{IH_nRST}	Chip reset release voltage	0.75 × VDD	—	VDD + 0.3	V
V_{IL_nRST}	Chip reset voltage	–0.3	—	0.25 × VDD	V

Note:
VDD is the I/O voltage for a particular power domain of pins.

4.1 Current Consumption Characteristics

With the use of advanced power-management technologies, the module can switch between different power modes. For details on different power modes, please refer to Section *RTC and Low-Power Management* in *ESP32-S2 User Manual*.

Table 7: Current Consumption Depending on RF Modes

Work mode	Description		Average	Peak
Active (RF working)	TX	802.11b, 20 MHz, 1 Mbps, @ 22.31dBm	190 mA	310 mA
		802.11g, 20 MHz, 54 Mbps, @ 25.00dBm	145 mA	220 mA
		802.11n, 20 MHz, MCS7, @ 24.23dBm	135 mA	200 mA
		802.11n, 40 MHz, MCS7, @ 22.86 dBm	120 mA	160 mA
	RX	802.11b/g/n, 20 MHz	63 mA	63 mA
		802.11n, 40 MHz	68 mA	68 mA

Note:

- The current consumption measurements are taken with a 3.3 V supply at 25 °C of ambient temperature at the RF port. All transmitters' measurements are based on a 50% duty cycle.
- The current consumption figures for in RX mode are for cases when the peripherals are disabled and the CPU idle.

Table 8: Current Consumption Depending on Work Modes

Work mode	Description		Current consumption (Typ)
Modem-sleep	The CPU is powered on	240 MHz	22 mA
		160 MHz	17 mA
		Normal speed: 80 MHz	14 mA
Light-sleep	—		550 μA
Deep-sleep	The ULP co-processor is powered on.		220 μA
	ULP sensor-monitored pattern		7 μA @1% duty
	RTC timer + RTC memory		10 μA
	RTC timer only		5 μA
Power off	CHIP_PU is set to low level, the chip is powered off.		0.5 μA

Note:

- The current consumption figures in Modem-sleep mode are for cases where the CPU is powered on and the cache idle.
- When Wi-Fi is enabled, the chip switches between Active and Modem-sleep modes. Therefore, current consumption changes accordingly.
- In Modem-sleep mode, the CPU frequency changes automatically. The frequency depends on the CPU load and the peripherals used.
- During Deep-sleep, when the ULP co-processor is powered on, peripherals such as GPIO and I^2C are able to operate.
- The "ULP sensor-monitored pattern" refers to the mode where the ULP coprocessor or the sensor works periodically. When touch sensors work with a duty cycle of 1%, the typical current consumption is 7 μA.

5.5 Wi-Fi RF Characteristics

5.5.1 Wi-Fi RF Standards

Table 9: Wi-Fi RF Standards

Name		Description
Center frequency range of operating channel [note1]		2412 ~ 2462 MHz
Wi-Fi wireless standard		IEEE 802.11b/g/n
Data rate	20 MHz	11b: 1, 2, 5.5 and 11 Mbps 11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 11n: MCS0-7, 72.2 Mbps (Max)
	40 MHz	11n: MCS0-7, 150 Mbps (Max)
Antenna type		PCB antenna, IPEX antenna

1. Device should operate in the center frequency range allocated by regional regulatory authorities. Target center frequency range is configurable by software.
2. For the modules that use IPEX antennas, the output impedance is 50 Ω. For other modules without IPEX antennas, users do not need to concern about the output impedance.

5.5.2 Transmitter Characteristics

Table 10: Transmitter Characteristics

Parameter	Rate	Unit
TX Power [note1]	802.11b:22.31dBm 802.11g:25.00dBm 802.11n20:24.23dBm 802.11n40:22.86dBm	dBm

1. Target TX power is configurable based on device or certification requirements.

5.5.3 Receiver Characteristics

Table 11: Receiver Characteristics

Parameter	Rate	Typ	Unit
RX Sensitivity	1 Mbps	–97	dBm
	2 Mbps	–95	
	5.5 Mbps	–93	
	11 Mbps	–88	
	6 Mbps	–92	

Parameter	Rate	Typ	Unit
RX Sensitivity	9 Mbps	–91	dBm
	12 Mbps	–89	
	18 Mbps	–86	
	24 Mbps	–83	
	36 Mbps	–80	
	48 Mbps	–76	
	54 Mbps	–74	
	11n, HT20, MCS0	–92	
	11n, HT20, MCS1	–88	
	11n, HT20, MCS2	–85	
	11n, HT20, MCS3	–82	
	11n, HT20, MCS4	–79	
	11n, HT20, MCS5	–75	
	11n, HT20, MCS6	–73	
	11n, HT20, MCS7	–72	
	11n, HT40, MCS0	–89	
	11n, HT40, MCS1	–85	
	11n, HT40, MCS2	–83	
	11n, HT40, MCS3	–79	
	11n, HT40, MCS4	–76	
	11n, HT40, MCS5	–72	
	11n, HT40, MCS6	–70	
	11n, HT40, MCS7	–68	
RX Maximum Input Level	11b, 1 Mbps	5	dBm
	11b, 11 Mbps	5	
	11g, 6 Mbps	5	
	11g, 54 Mbps	0	
	11n, HT20, MCS0	5	
	11n, HT20, MCS7	0	
	11n, HT40, MCS0	5	
	11n, HT40, MCS7	0	
Adjacent Channel Rejection	11b, 11 Mbps	35	dB
	11g, 6 Mbps	31	
	11g, 54 Mbps	14	
	11n, HT20, MCS0	31	
	11n, HT20, MCS7	13	
	11n, HT40, MCS0	19	
	11n, HT40, MCS7	8	

6. Physical Dimensions and PCB Land Pattern

6.1 Physical Dimensions

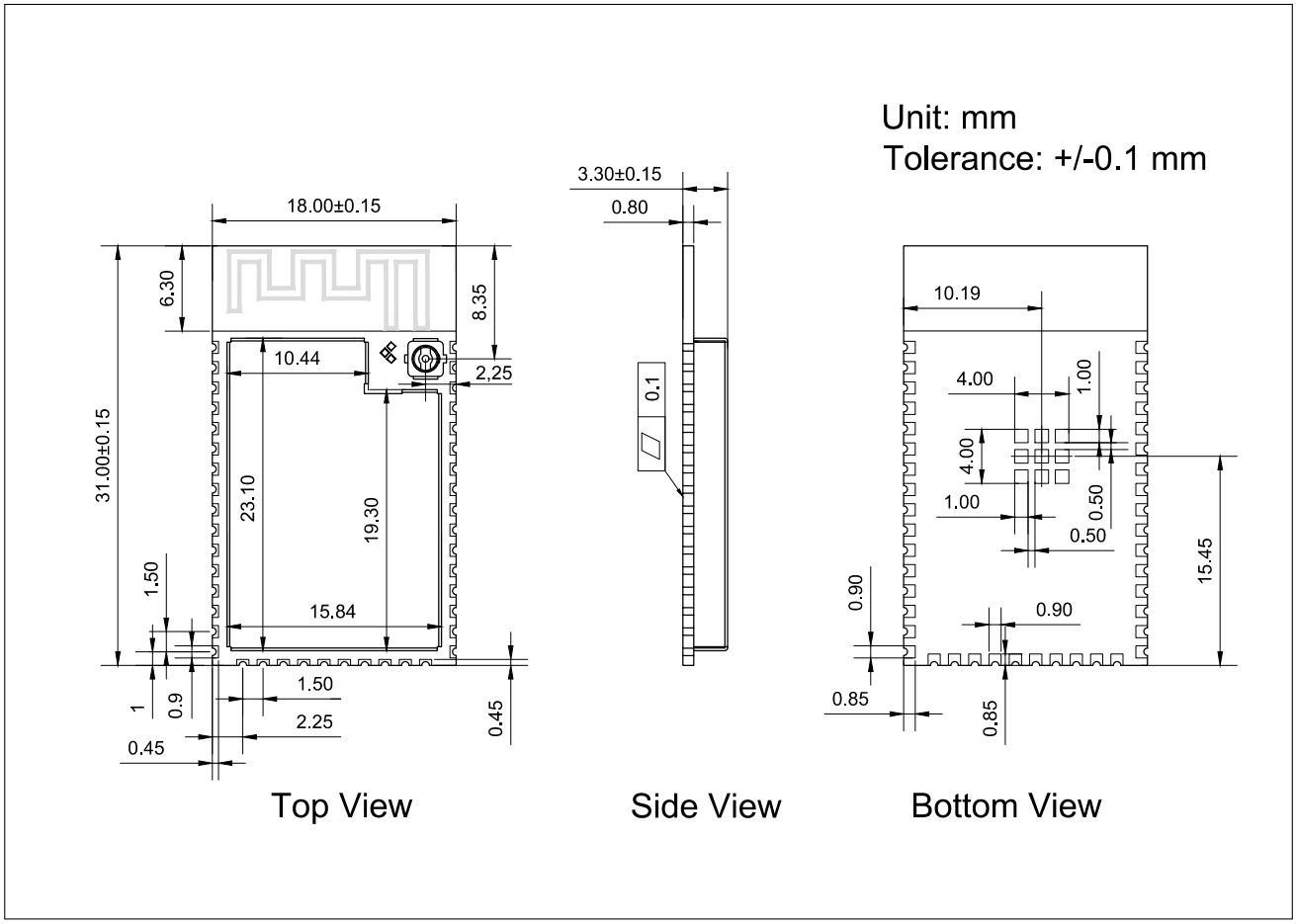


Figure 6: Physical Dimensions

6.2 Recommended PCB Land Pattern

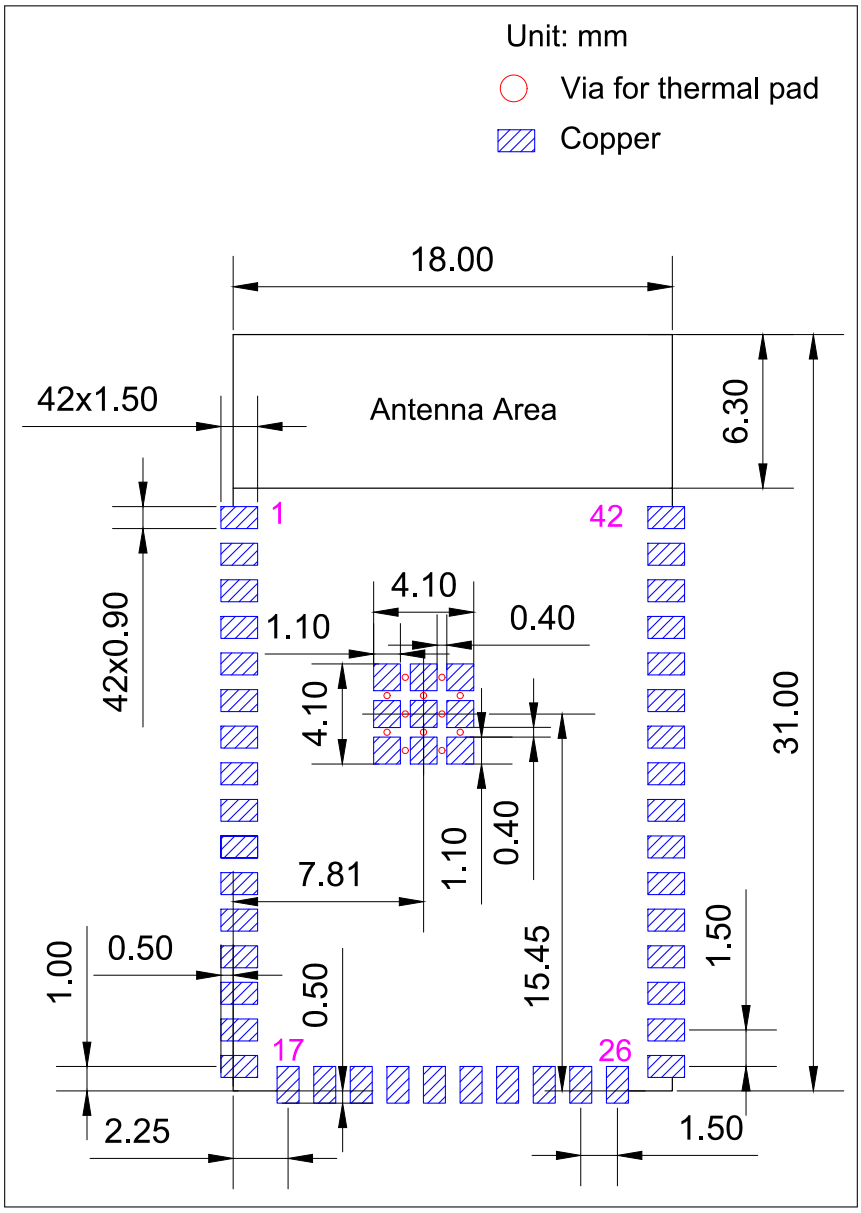
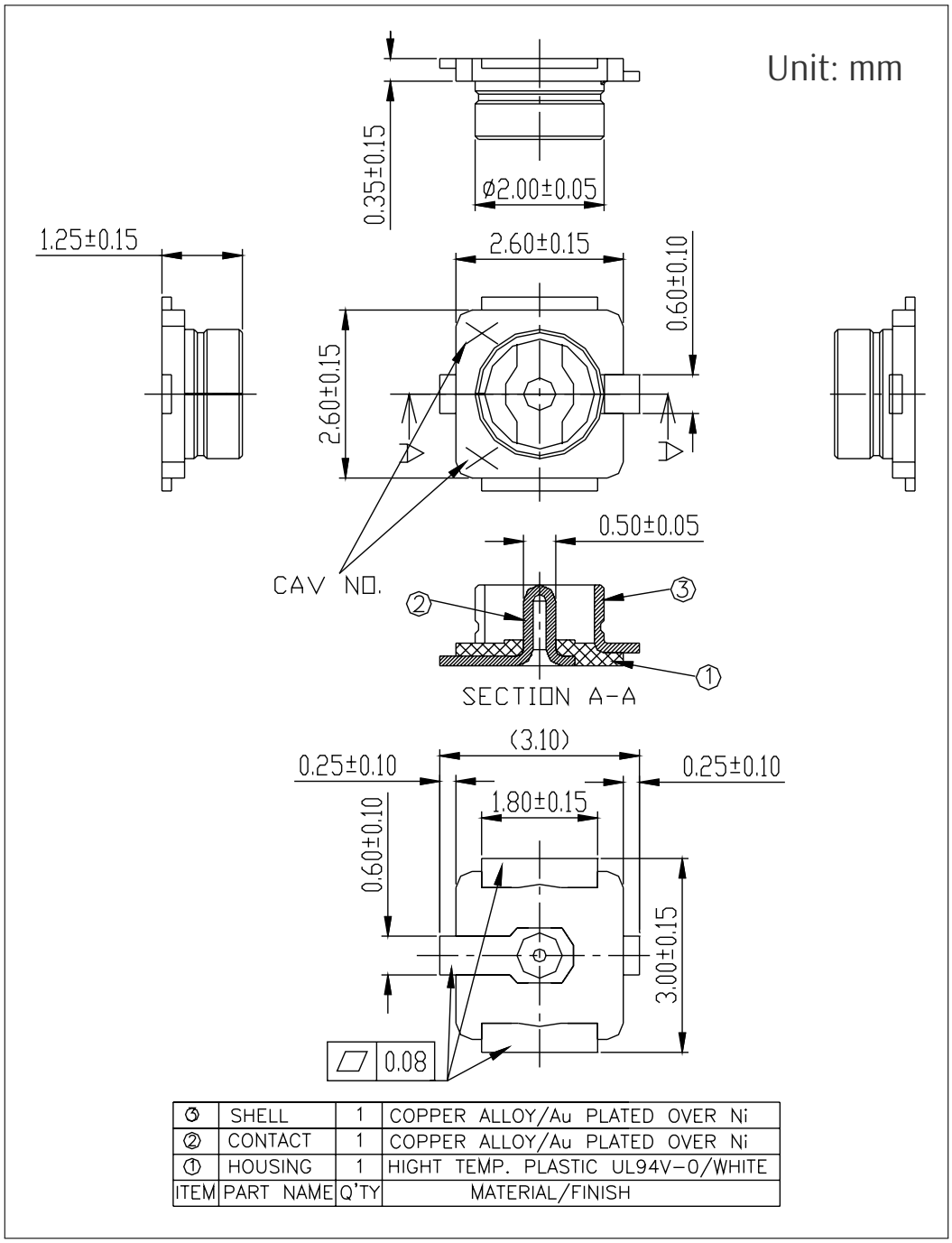


Figure 7: Recommended PCB Land Pattern

6.3 U.FL Connector Dimensions



ITEM	PART NAME	Q'TY	MATERIAL/FINISH
③	SHELL	1	COPPER ALLOY/Au PLATED OVER Ni
②	CONTACT	1	COPPER ALLOY/Au PLATED OVER Ni
①	HOUSING	1	HIGHT TEMP. PLASTIC UL94V-0/WHITE

Figure 8: U.FL Connector Dimensions

7. Product Handling

7.1 Storage Condition

The products sealed in Moisture Barrier Bag (MBB) should be stored in a noncondensing atmospheric environment of < 40 °C/90%RH.

The module is rated at moisture sensitivity level (MSL) 3.

After unpacking, the module must be soldered within 168 hours with factory conditions 25±5 °C/60%RH. The module needs to be baked if the above conditions are not met.

7.2 ESD

- Human body model (HBM): 2000 V
- Charged-device model (CDM): 500 V
- Air discharge: 6000 V
- Contact discharge: 4000 V

7.3 Reflow Profile

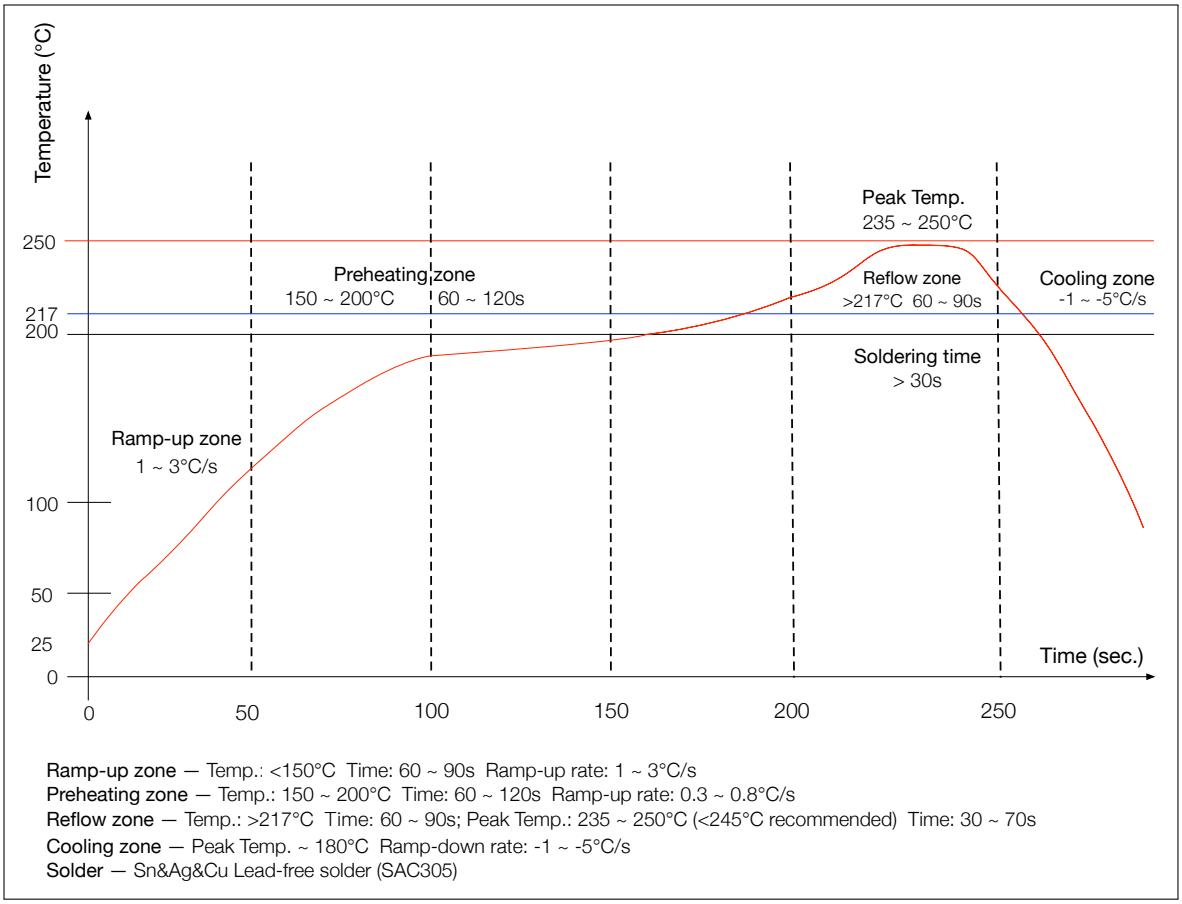


Figure 9: Reflow Profile

Note:

Solder the module in a single reflow. If the PCBA requires multiple reflows, place the module on the PCB during the final reflow.

8. MAC Addresses and eFuse

The eFuse in ESP32-S2 has been burnt into 48-bit mac_address. The actual addresses the chip uses in station and AP modes correspond to mac_address in the following way:

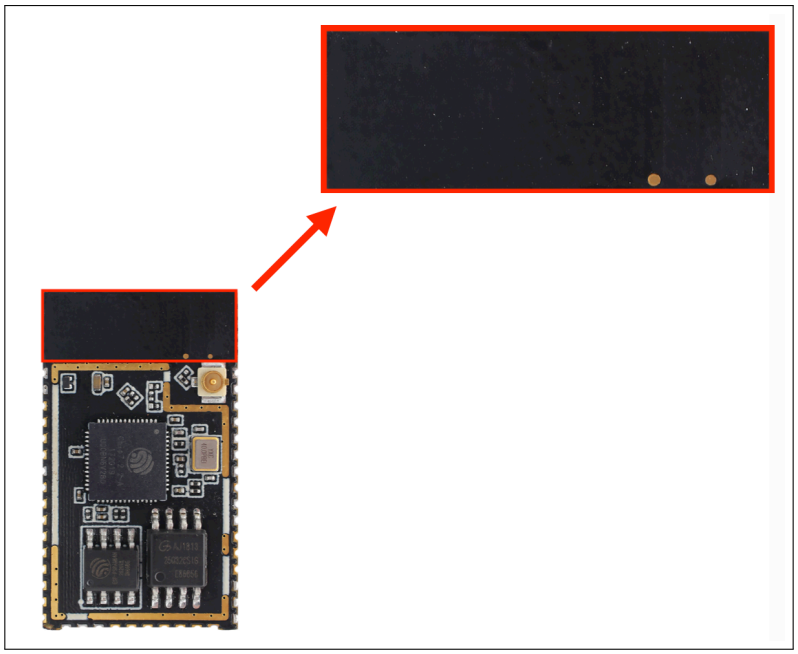
- Station mode: mac_address
- AP mode: mac_address + 1

There are seven blocks in eFuse for users to use. Each block is 256 bits in size and has independent write/read disable controller. Six of them can be used to store encrypted key or user data, and the remaining one is only used to store user data.

9. Antenna Specifications

9.1 PCB Antenna

Model: ESP ANT B

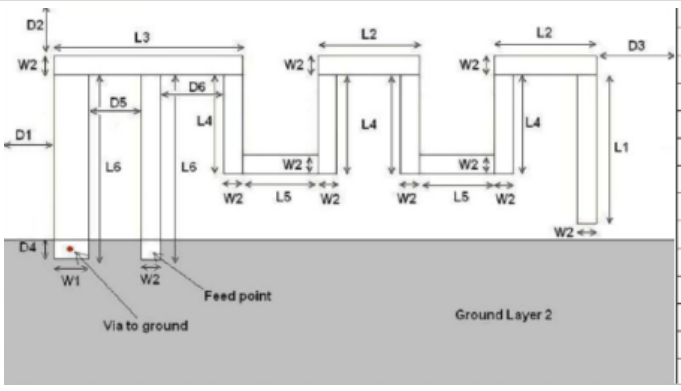


Assembly: PTH

Gain:

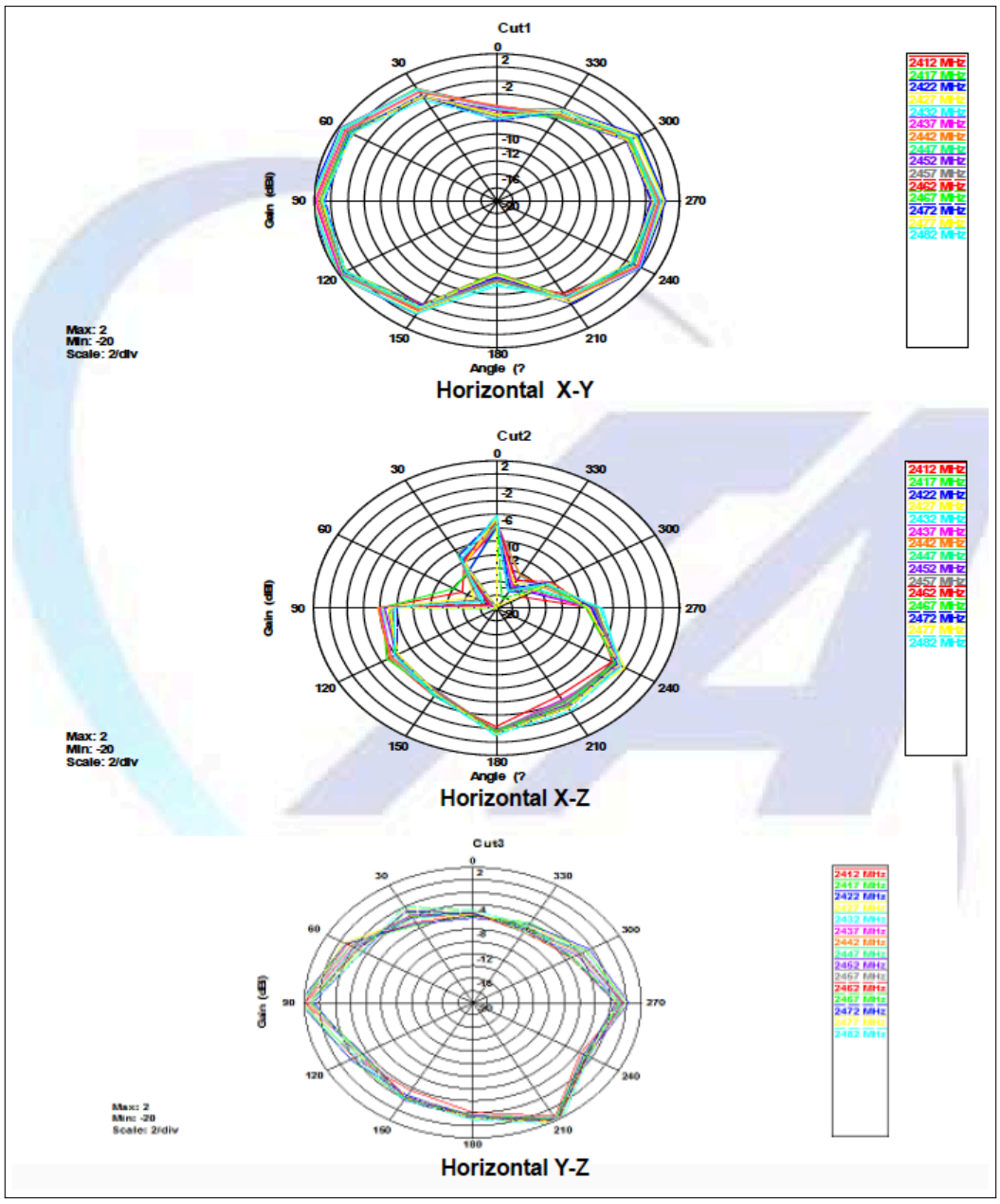
Model	Test Item	Test State	Frequency (MHz)	Efficiency (%)	Gain (dB)	Note
ESP-ANT B	Gain	Free Space	2412	73.79	2.39	Vertical 30°
			2417	77.04	2.97	
			2422	79.83	2.80	
			2427	81.19	2.89	
			2432	80.54	3.04	
			2437	76.86	2.86	
			2442	76.17	2.99	
			2447	73.99	2.96	
			2452	72.00	2.80	
			2457	70.71	2.72	
			2462	71.31	2.94	
			2467	71.32	3.12	
			2472	72.03	3.28	
			2477	72.71	3.24	
			2482	75.42	3.40	

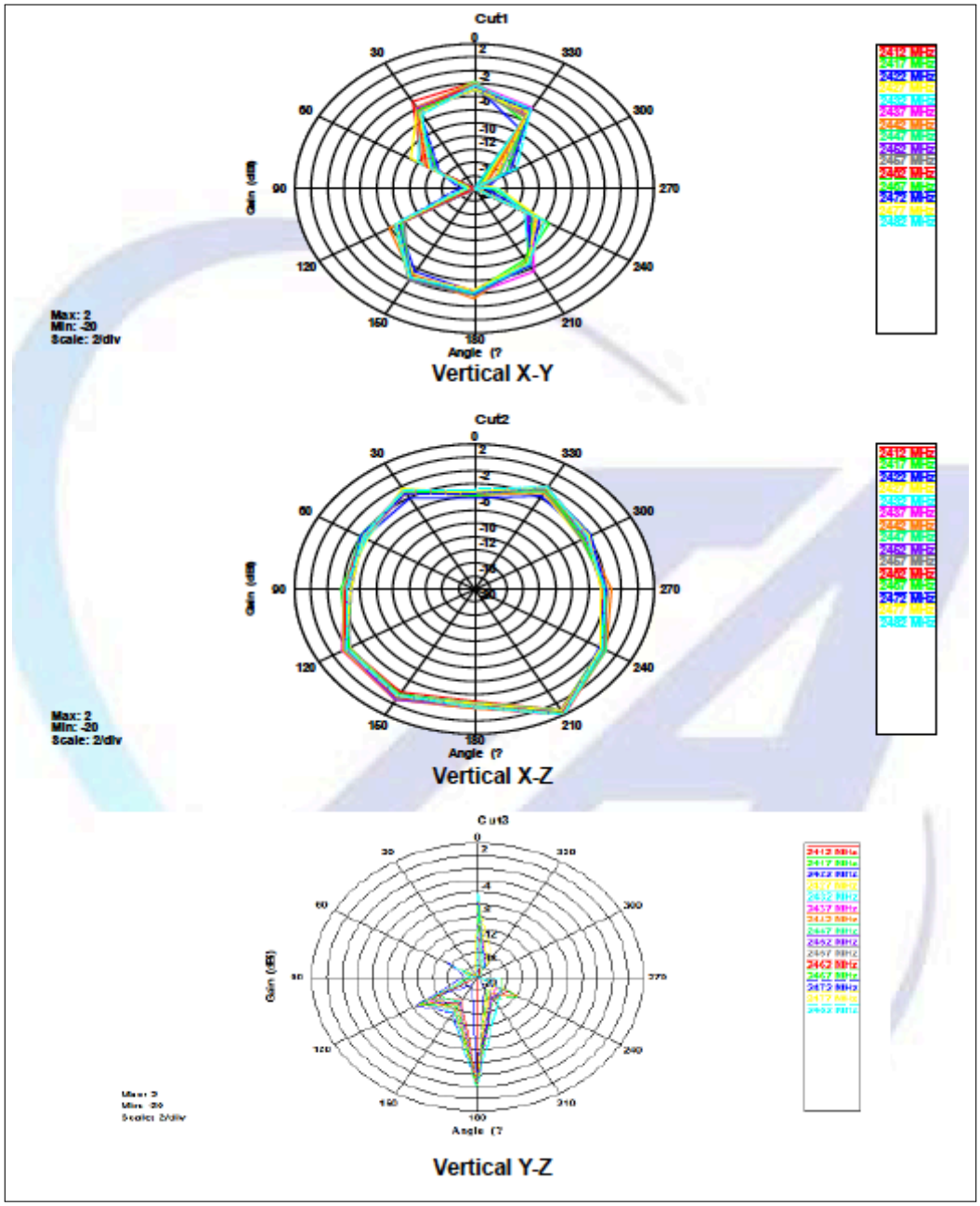
Dimensions:



L1	3.94
L2	2.70
L3	5.00
L4	2.64
L5	2.00
L6	4.90
W1	0.90
W2	0.50
D1	0.50
D2	0.30
D3	0.30
D4	0.50
D5	1.40
D6	1.70

Pattern Plots:




Cut1
Max: 2
Min: -20
Scale: 2/div
Vertical X-Y
Cut2
Max: 2
Min: -20
Scale: 2/div
Vertical X-Z
Cut3
Vertical Y-Z

9.2 IPEX Antenna

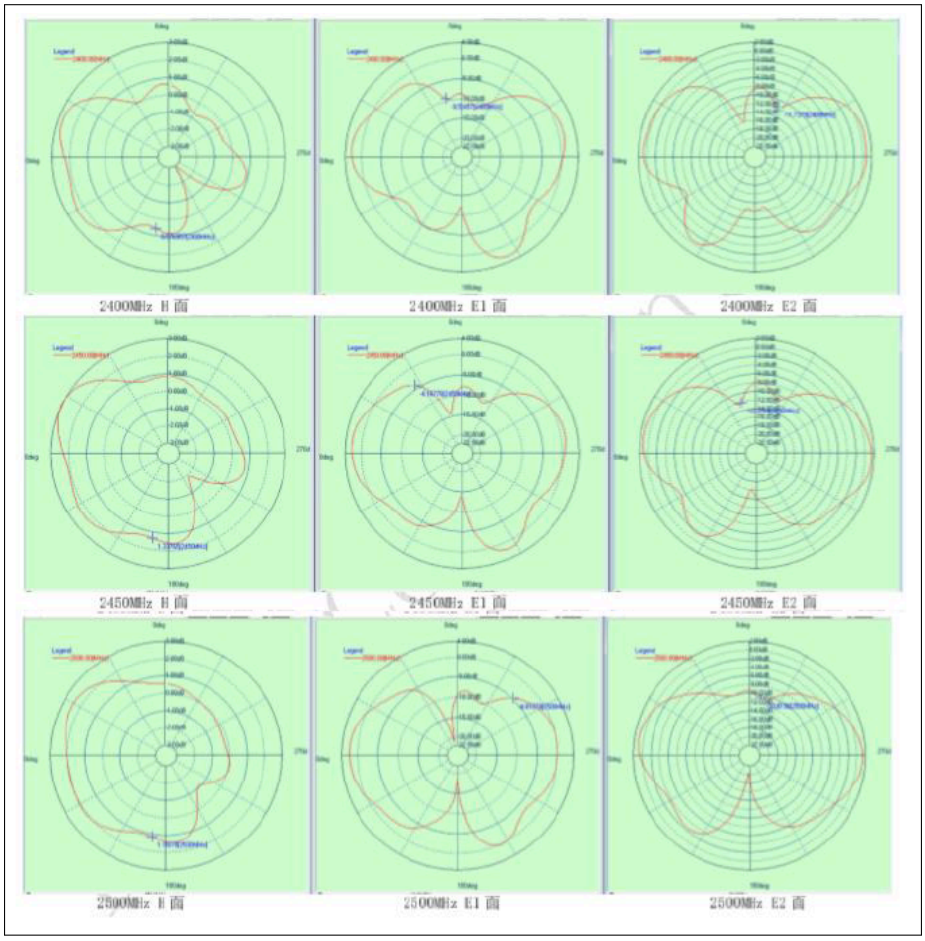
Specifications:

电性能指标 Electrical Specifications	
频率范围 Frequency Range (MHz)	2400-2500
频带宽度 Bandwidth (MHz)	100
输入阻抗 Input Impendence (Ω)	50
电压驻波比 VSWR	<2.5
增益 Gain (dBi)	>1.0
极化形式 Polarization Type	垂直极化 Vertical
机械指标 Mechanical Specifications	
天线长度 Antenna Length (mm)	100mm
连接器型号 Connect Type	iPex 一代
工作温度 Operatin Temp (℃)	-30~70
储存温度 Storing Temp(℃)	-30~70
外壳颜色 Radome Color	黑色 Black

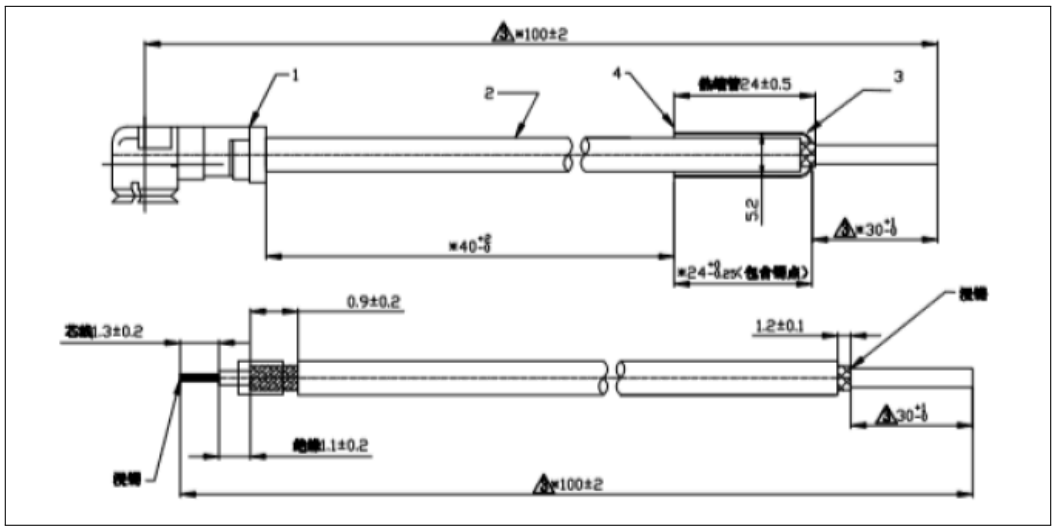
Gain:

Freq. (MHz)	Effi.	Gain (dBi)
2400	78%	2.17
2410	78%	2.19
2420	79%	2.31
2430	79%	2.26
2440	78%	2.21
2450	79%	2.33
2460	78%	2.32
2470	76%	2.14
2480	75%	2.05
2490	74%	2.02
2500	72%	1.83
Avg.	77%	2.17

Directivity Diagram:



Dimensions:



10. Learning Resources

10.1 Must-Read Documents

The following link provides documents related to ESP32-S2.

- *ESP32-S2 User Manual*
  This document provides an introduction to the specifications of the ESP32-S2 hardware, including overview, pin definitions, functional description, peripheral interface, electrical characteristics, etc.
- *ESP-IDF Programming Guide*
  It hosts extensive documentation for ESP-IDF ranging from hardware guides to API reference.
- *ESP32-S2 Technical Reference Manual*
  The manual provides detailed information on how to use the ESP32-S2 memory and peripherals.
- *Espressif Products Ordering Information*

10.2 Must-Have Resources

Here are the ESP32-S2-related must-have resources.

- ESP32-S2 BBS
  This is an Engineer-to-Engineer (E2E) Community for ESP32-S2 where you can post questions, share knowledge, explore ideas, and help solve problems with fellow engineers.

Revision History

Date	Version	Release notes
2020-03-10	V0.5	Preliminary release

OEM Guidance

1. Applicable FCC rules

   This module is granted by Single Modular Approval. It complies to the requirements of FCC part 15C, section 15.247 rules.

2. The specific operational use conditions

   This module can be used in IoT devices. The input voltage to the module is nominally 3.3V-3.6 V DC. The operational ambient temperature of the module is -30 to 85 degree C. Only the embedded PCB antenna is allowed. Any other external antenna is prohibited.

3. Limited module procedures

   N/A

4. Trace antenna design

   N/A

5. RF exposure considerations

   The equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body. If the equipment

built into a host as a portable usage, the additional RF exposure evaluation may

be required as specified by 2.1093.

6. Antenna

Antenna type: PCB antenna/Dipole Antenna; Peak gain: 3.40dBi /2.33dBi

7. Label and compliance information

An exterior label on OEM's end product can use wording such as the following:
"Contains Transmitter Module FCC ID: 2AC7Z-ESP32S2WROOM" or
"Contains FCC ID: 2AC7Z-ESP32S2WROOM."

8. Information on test modes and additional testing requirements

a)The modular transmitter has been fully tested by the module grantee on the required number of channels,modulation types, and modes, it should not be necessary for the host installer to re-test all the available transmitter modes or settings. It is recommended that the host product manufacturer, installing the modular transmitter,perform some investigative measurements to confirm that the resulting composite system does not exceed the spurious emissions limits or band edge limits (e.g., where a different antenna may be causing additional emissions).
b)The testing should check for emissions that may occur due to the intermixing of emissions with the other transmitters, digital circuitry, or due to physical properties of the host product (enclosure). This investigation is especially important when integrating multiple modular transmitters where the certification is based on testing each of them in a stand-alone configuration. It is important to note that host product manufacturers should not assume that because the modular transmitter is certified that they do not have any responsibility for final product compliance.
c)If the investigation indicates a compliance concern the host product manufacturer is obligated to mitigate the issue. Host products using a modular transmitter are subject to all the applicable individual technical rules as well as to the general conditions of operation in Sections 15.5, 15.15, and 15.29 to not cause interference. The operator of the host product will be obligated to stop operating the device until the interference have been corrected .

9. Additional testing, Part 15 Sub part B disclaimer The final host / module combination need to be evaluated against the FCC Part 15B criteria for unintentional radiators in order to be properly authorized for operation as a Part 15 digital device.

The host integrator installing this module into their product must ensure that the final composite product complies with the FCC requirements by a technical assessment or evaluation to the FCC rules, including the transmitter operation and should refer to guidance in KDB 996369. For host products with certified modular transmitter, the frequency range of investigation of the composite system is specified by rule in Sections 15.33(a)(1) through (a)(3), or the range applicable to the digital device, as shown in Section 15.33(b)(1), whichever is the higher frequency range of investigation When testing the host product, all the transmitters must be operating.The transmitters can be enabled by using publicly-available drivers and turned on, so the transmitters are active. In certain conditions it might be appropriate to use a technology-specific call box (test set) where accessory 50 devices or drivers are not available. When testing for emissions from the unintentional radiator, the transmitter shall be placed in the receive mode or idle mode, if possible. If receive mode only is not possible then, the radio shall be passive (preferred) and/or active scanning. In these cases, this would need to enable activity on the communication BUS (i.e., PCIe, SDIO, USB) to ensure the unintentional radiator circuitry is enabled. Testing laboratories may need to add attenuation or filters depending on the signal strength of any active beacons (if applicable) from the enabled radio(s). See ANSI C63.4, ANSI C63.10 and ANSI C63.26 for further general testing details.
The product under test is set into a link/association with a partnering device, as per the normal intended use of the product. To ease testing, the product under test is set to transmit at a high duty cycle, such as by sending a file or streaming some media content.

FCC Warning:

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user’s authority to operate the equipment. This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation